FY2025
Business Results

May 11, 2026

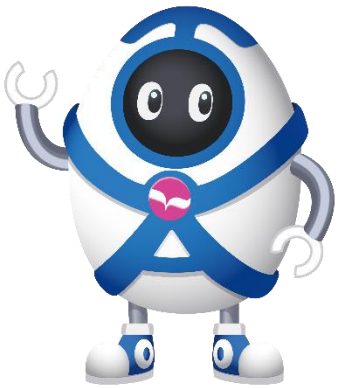


Table of Contents

Table of Contents

FY2025 Summary

(100 Million yen)

Orders	Net Sales	Operating Profit	Ordinary Profit	Net Profit
595.6	543.6	69.1	69.4	45.9
(YoY +25.6%)	(YoY +1.7%)	(YoY -22.1%)	(YoY -26.1%)	(YoY -43.4%)

Orders

・It remained strong from the second quarter onward, mainly for AI and data centers, and recorded the second highest orders ever.
・Orders for compression equipment and molds reached a record high due to increased investment in memory and advanced packages.

Net Sales

・As with orders, sales for AI and data centers, such as memory and advanced packages, were strong, recording record highs.
・Sales of singulation equipment increased significantly due to increased investment in memory.

Profit

・Although sales increased, profit decreased due to fluctuations in the product mix and the impact of additional costs associated with initial deliveries.

FY2025 Consolidated Financial Results

(100 Million yen)

	FY2024 Results	FY2025 Results	YoY	FY2025 Forecast (Revised)	Vs.Fcst
Net Sales	534.7	543.6	+ 8.8 (+ 1.7%)	545.0	- 1.3 (- 0.2%)
Operating Profit	88.8	69.1	- 19.6 (- 22.1%)	70.0	- 0.8 (- 1.2%)
Operating margin	16.6%	12.7%	- 3.9pt	12.8%	- 0.1pt
Ordinary Profit	94.0	69.4	- 24.5 (- 26.1%)	70.0	- 0.5 (- 0.8%)
Net Profit	81.2	45.9	- 35.2 (- 43.4%)	49.5	- 3.5 (- 7.2%)

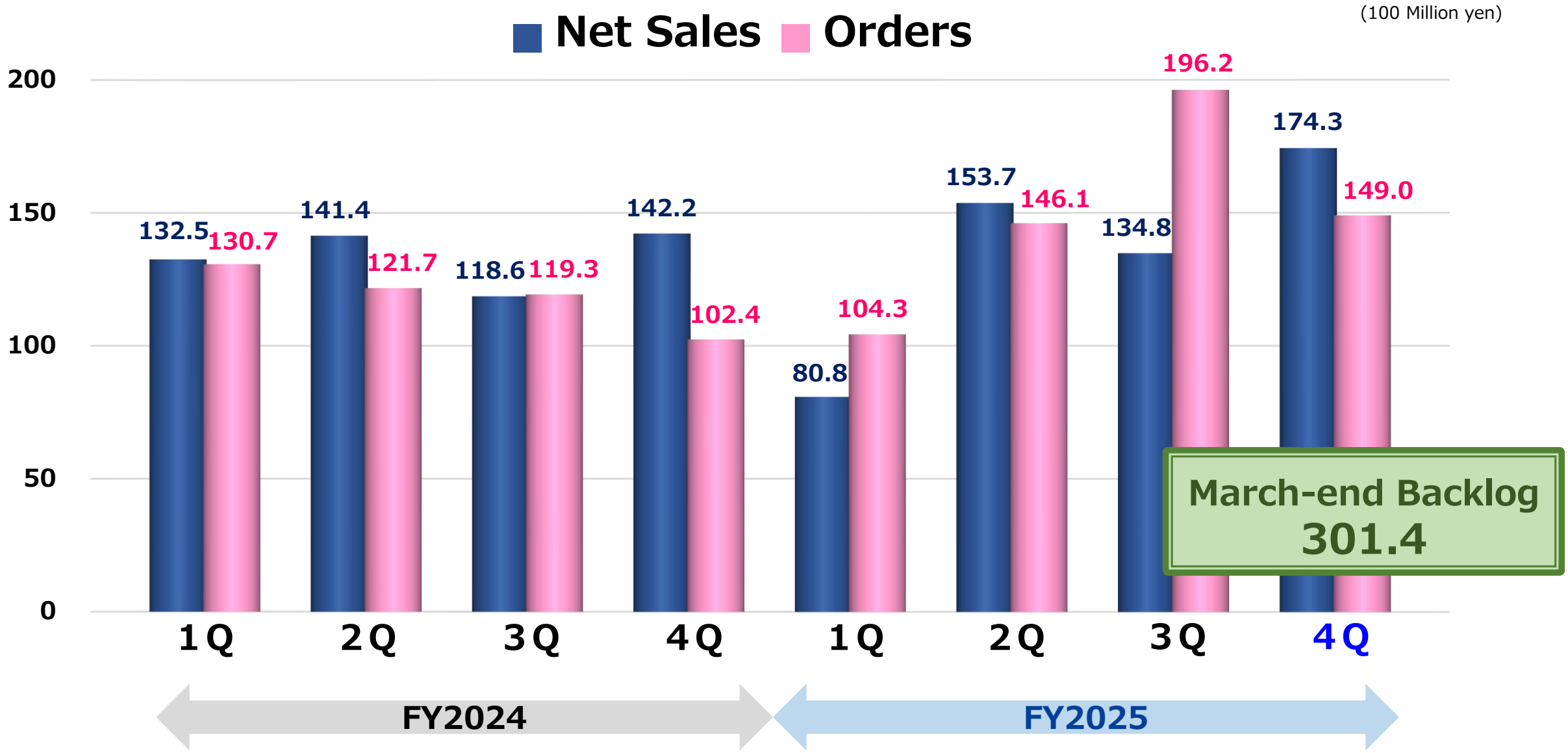
※Net Profit= Profit attributable to owners of parent

FY2025 Net Sales by Business Segment

(100 Million yen)

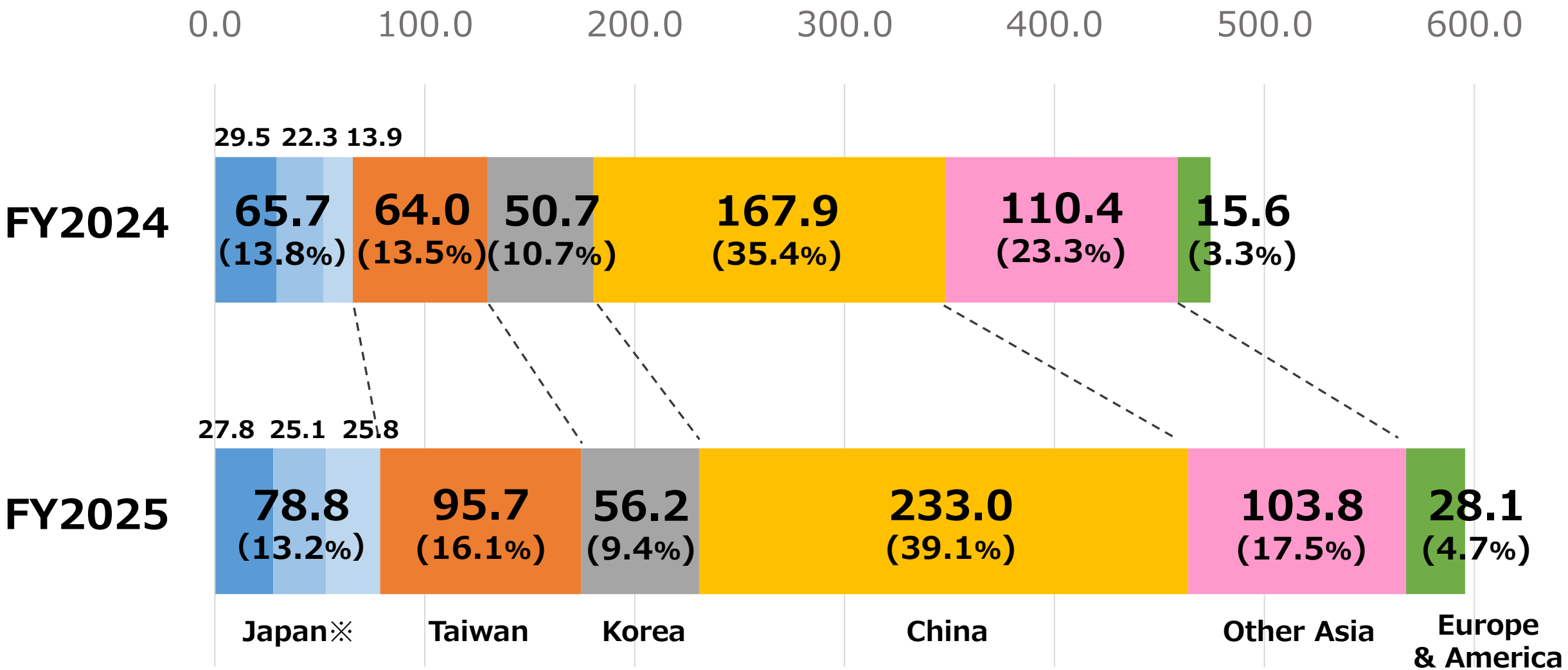
	FY2024 Results	FY2025 Results	YoY	FY2025 Forecast (Revised)	Vs.Fcst
Net Sales	534.7	543.6	+ 8.8 (+ 1.7%)	545.0	- 1.3 (- 0.2%)
Semiconductor	395.3	403.9	+ 8.6 (+ 2.2%)	399.8	+ 4.1 (+ 1.0%)
Medical Device	22.6	24.8	+ 2.2 (+ 9.9%)	25.0	- 0.1 (- 0.7%)
New Business	94.2	94.7	+ 0.5 (+ 0.6%)	100.2	- 5.3 (- 5.4%)
Laser	22.6	20.0	- 2.5 (- 11.0%)	20.0	+ 0.0 (+ 0.4%)

Net Sales and Orders Trend



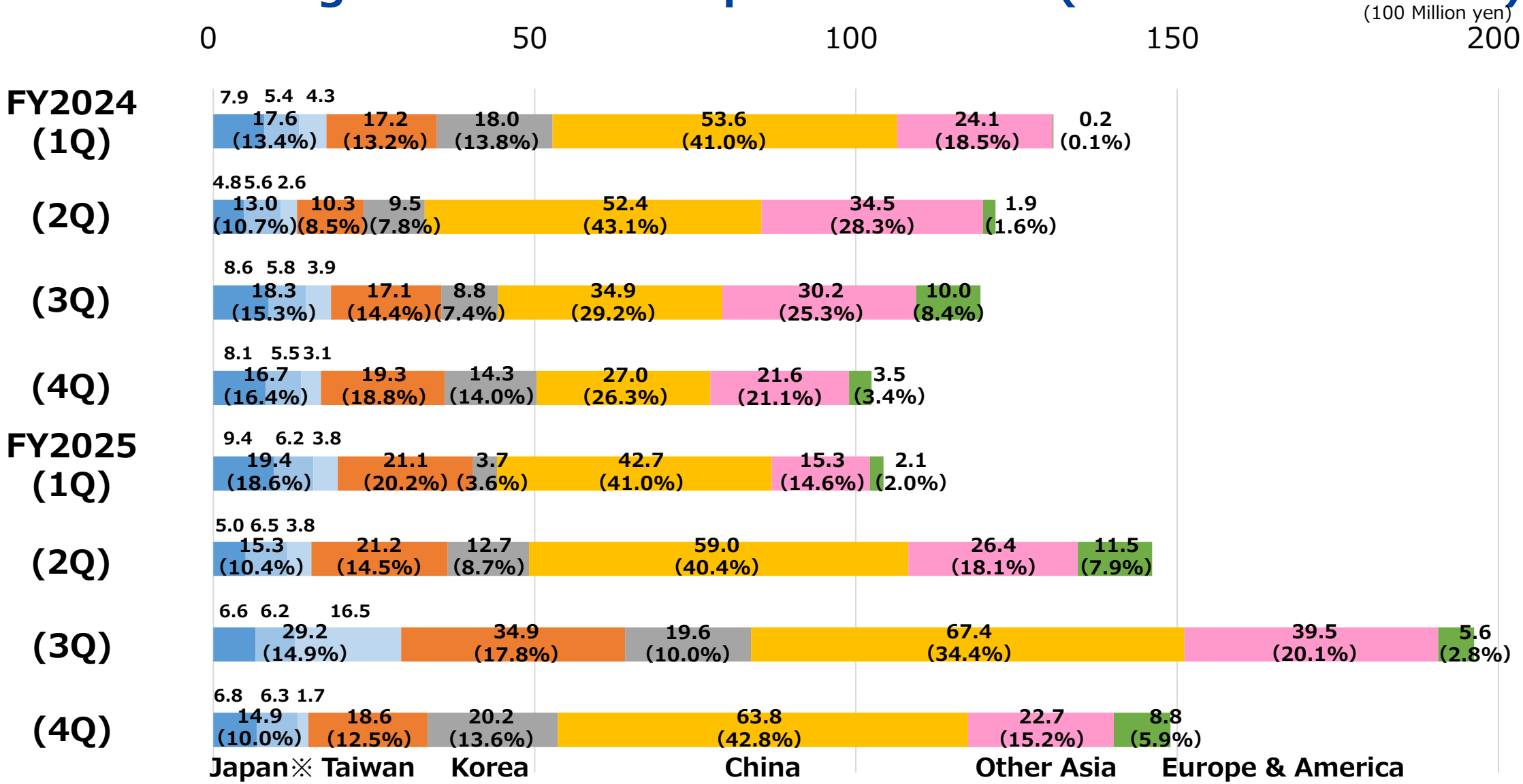
Regional Order Composition Ratio (Destination-Based)

(100 Million yen)



※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

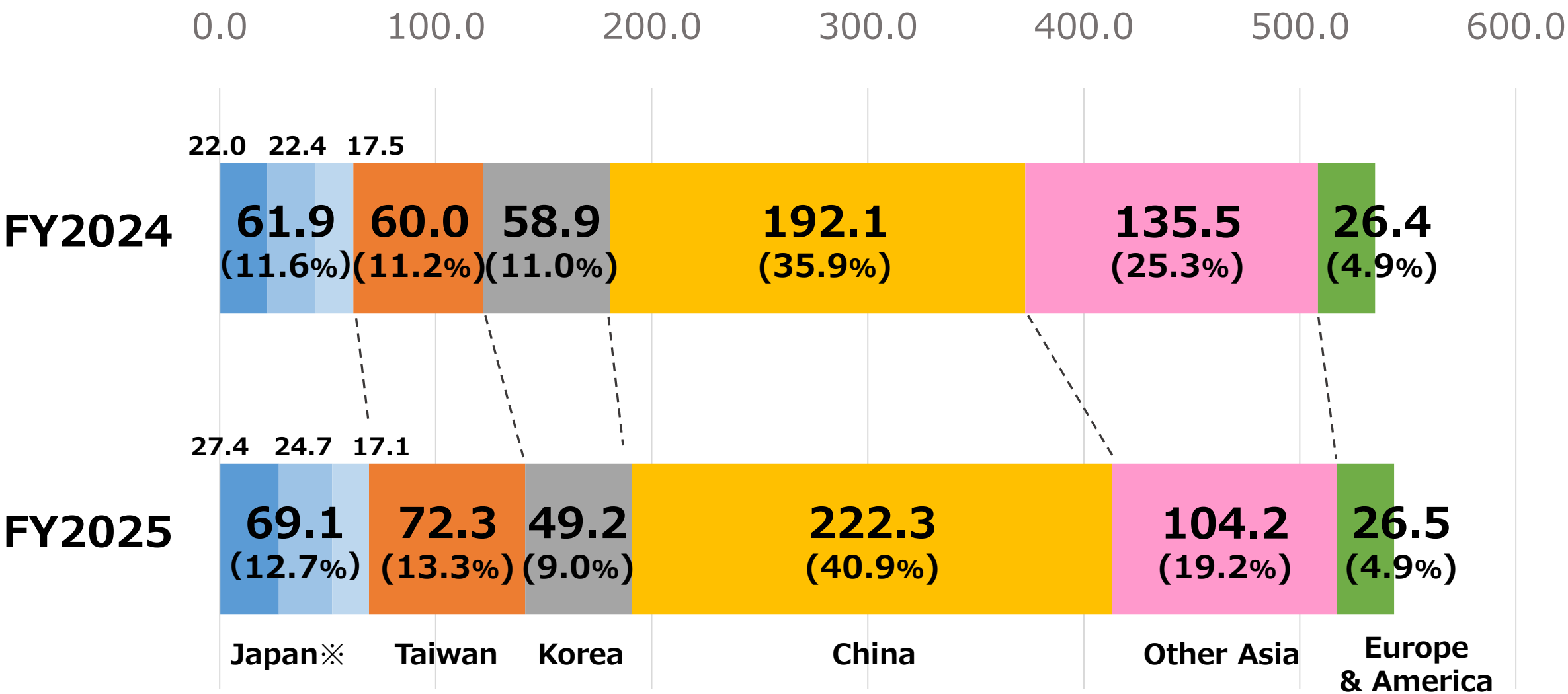
Trend of Regional Order Composition Ratio (Destination-Based)



※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

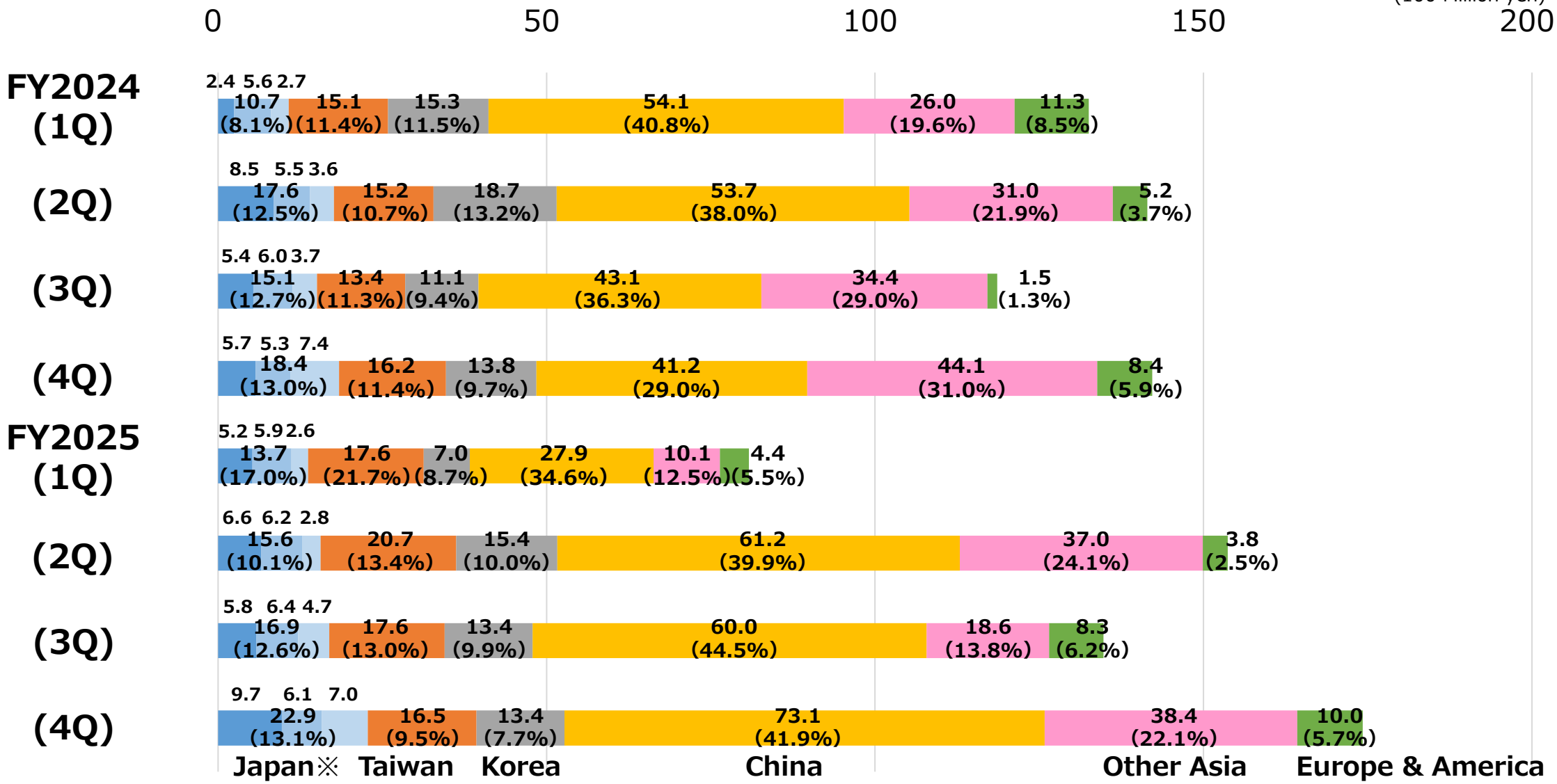
Regional Sales Composition Ratio (Destination-Based)

(100 Million yen)



※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

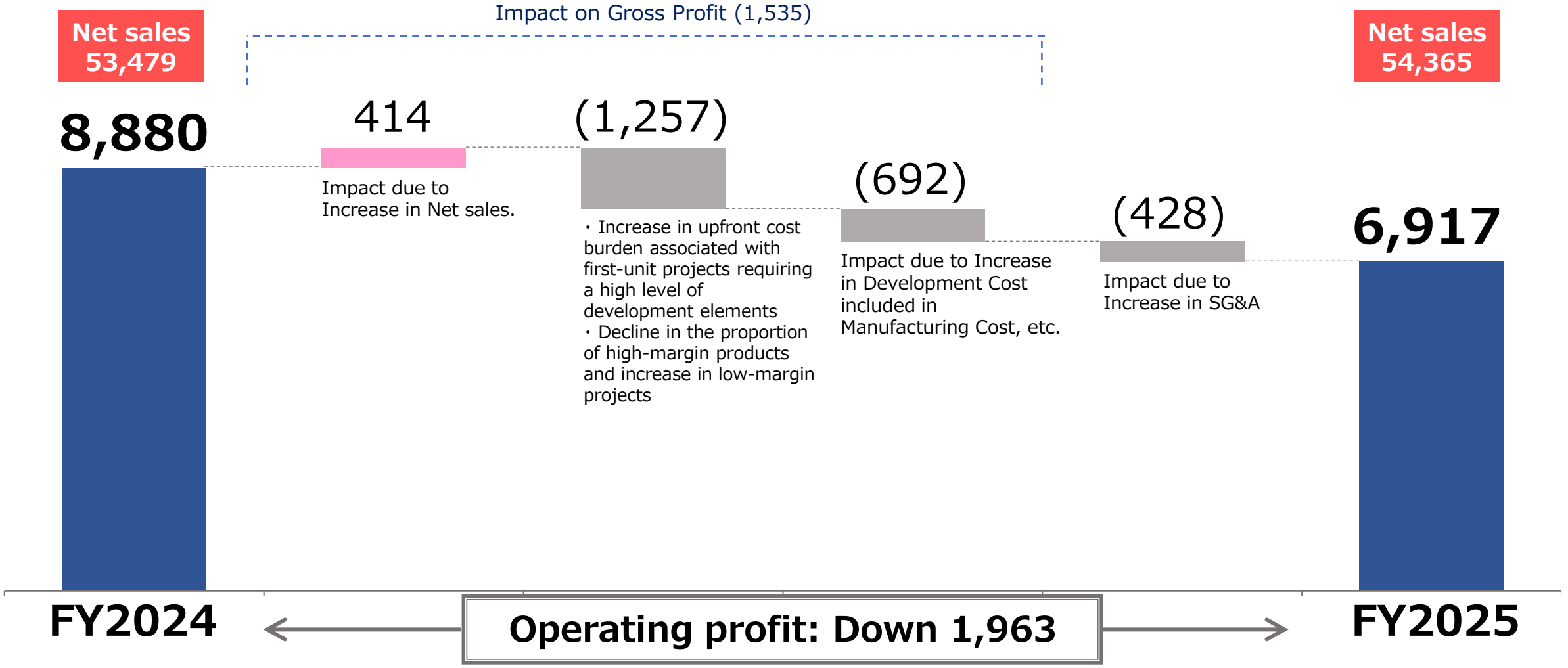
Trend of Regional Sales Composition Ratio (Destination-Based)



※In Japan, from left: Semiconductor Business (including new businesses), Medical Device Business, Laser Business

FY2025 Operating Profit Variance Analysis (YoY)

(Million yen)



※Yen amounts are rounded down to millions.

Table of Contents

FY2026 Forecast

(100 Million yen)

	FY2025 Results	FY2026 Forecast	Variance	YoY
Net Sales	543.6	640.0	+ 96.3	+ 17.7%
Operating Profit	69.1	102.4	+ 33.2	+ 48.0%
Operating margin	12.7%	16.0%	+ 3.3pt	–
Ordinary Profit	69.4	102.4	+ 32.9	+ 47.4%
Net Profit	45.9	70.0	+ 24.0	+ 52.4%

※Net Profit= Profit attributable to owners of parent

FY2026 Forecast of Net Sales by Business Segment

(100 Million yen)

	FY2025 Results	FY2026 Forecast	Variance	YoY
Net Sales	543.6	640.0	+ 96.3	+ 17.7%
Semiconductor	403.9	484.3	+ 80.3	+ 19.9%
Medical Device	24.8	25.5	+ 0.6	+ 2.5%
New Business	94.7	97.7	+ 2.9	+ 3.1%
Laser	20.0	32.5	+ 12.4	+ 61.9%

Capital Investment & Dividend Forecast

	FY2025 Records	FY2026 Forecast
Capital Expenditure (100 Million yen)	41.9	55.0
Dividends (yen)	20.0	24.0

▶ Major plan of Capital Expenditure

- Regarding smart factory
- Increase production capacity by introducing new production facilities or updating facilities at each factory
- Enhancement of laboratory capabilities
- Investment for DX

◆ In addition, M&A and other initiatives will be implemented proactively.

※We plan to increase the dividend by 4.0 yen to 24.0 yen per share, in line with our policy of stable and continuous dividend payments.

Market Outlook

Orders

- Investment in AI and data centers continues to drive growth.
- Investment in mass production of PLP for advanced packages is expected to start.

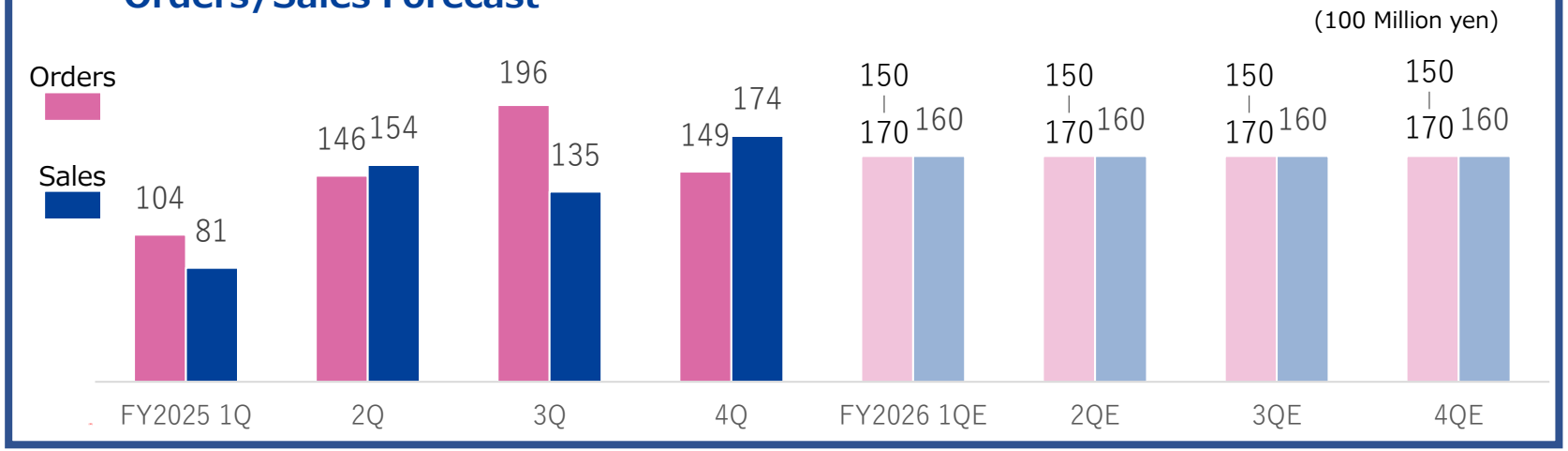
Sales

- Stable sales are expected based on the order backlog and the current order level.

Profit

- With the sales increase, margins are expected to improve YoY.
- Prioritize strengthening the market position in WLP, while expecting a gradual improvement in profit margins.

Orders/Sales Forecast



Orders Forecast

(100 Million yen)

1Q	2Q
150-170	150-170
3Q	4Q
150-170	150-170

Profit & Loss Forecast

(100 Million yen)

Net Sales	640.0
Operating Profit	102.4
Ordinary Profit	102.4
Net Profit	70.0

Table of Contents

Forecast of order trends in major regions

China	▶ Solid investment in the domestic production of EVs and power modules. ▶ Related investments continue against the backdrop of tight memory supply and demand.
Taiwan	▶ Production at OSAT expands in response to increased demand for AI servers. ▶ PLP mass production investment will start after second half of the year.
Korea	▶ Due to customer factory space constraints, HBM investment will be started after the second half of the year. ▶ Investment in general-purpose memory is currently increasing
Other Asia	▶ Demand for AI and data centers is resilient. ▶ Expansion of investment associated with the start of mass production in India.

HBM & Advanced Package Trends

Market environment

- The semiconductor market is being driven by growth in AI-related applications such as HBM, GPUs, and AI accelerators.

HBM

- Against the backdrop of strong demand, memory manufacturers are increasing their investments in HBM mass production.
- Production using MUF technology continues due to cost and technical challenges.

Advanced Package

- For custom ASICs, investment in advanced packaging by OSAT companies is increasing.
- An increase in PLP investment is expected to expand production capacity and improve manufacturing efficiency.

Molding innovation Ⅳ : INNOMS

Semiconductor mass production costs halved

Toward a new standard as the "4th Molding innovation"!

Concept

- ✓ Low cost
- ✓ Mass production
- ✓ Reducing environmental impact

★ New Equipment Features

① Approx. 50% Reduction in Mass Production Costs

② Double Productivity per Unit

③ Approx. 40% Reduction in Footprint

④ Approx. 50% Lower Power Consumption;
Approx. 25% Reduction in Consumables & Materials

⑤ Broad Package Compatibility (Memory, Logic, QFN, RF Modules, etc.)

TOWA Vision 2032

「To the top of the world with change」

《Contact》
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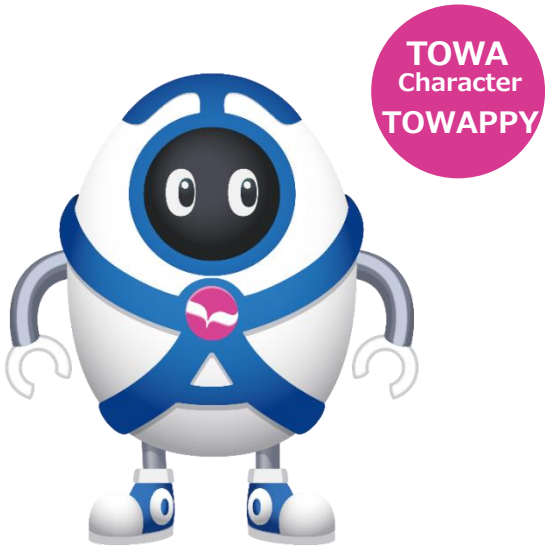
5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto 601-8105
Telephone number : +81-75-692-0251

Reference materials

Corporate Overview



Profile of TOWAPPY

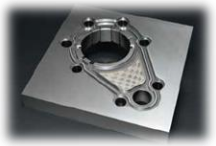
[1] Name: TOWAPPY
[2] Origin of the name:
Delivering happiness to the world from TOWA.
[3] Favorite word: Challenge!

Company name	TOWA CORPORATION
Business	Semiconductor Business, New Business, Medical Device Business, Laser Processing Machines Business
Address	5 Kamichoshi-cho, Kamitoba, Minami-ku, Kyoto
Established	April 1979
Chairman & CEO	Hirokazu Okada
President Executive Officer	Muneo Miura
Number of Employee	2,211 (consolidated) [as of March 2026]
Paid-in Capital	8.9 billion yen
Code Number	6315

TOWA's Business

New Business

・TSS
(Total Solution Service)
・Tools for precision process,
Consignment processing
・Fine process
・Coating



Consignment processing

Remodeling, Repair,
Preventative Maintenance

Fine process
technology

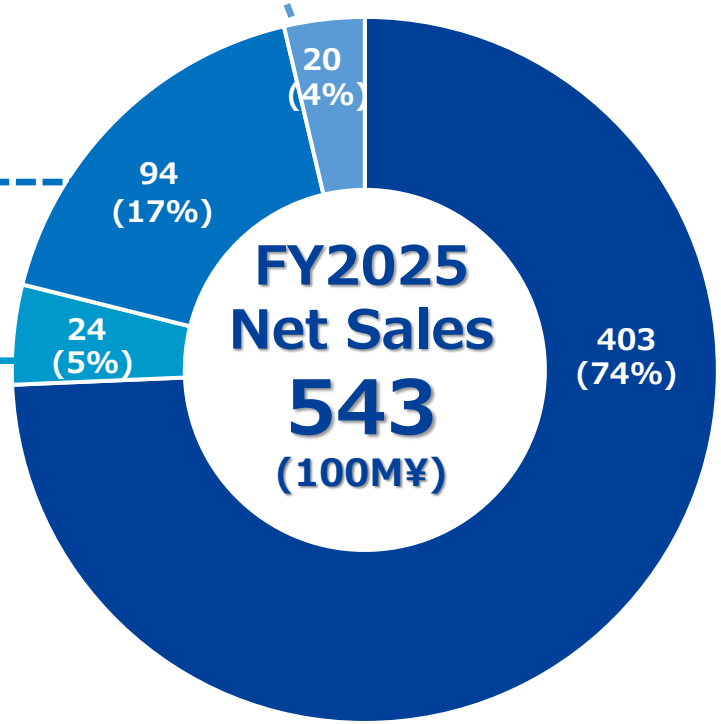
Tool (end mill)

Laser Processing Machines Business

・Laser Trimmer
・Wafer Marker
・Laser Welder

Laser Trimmer
Model SL432R

Wafer Marker
Model SL473GS3



Medical Device Business

・Fine plastic products
・Medical products

Component for IV drip

Component for syringe

Semiconductor Business

・Precision molds, Molding equipment and Singulation equipment for semiconductor manufacturing

Transfer Mold

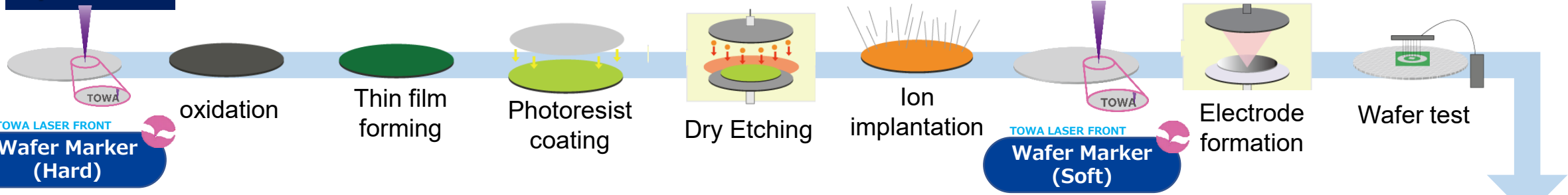
Molding Equipment
Model PMC 2030-D

Compression Mold

Molding Equipment
Model CPM 1080

Semiconductor Manufacturing Process

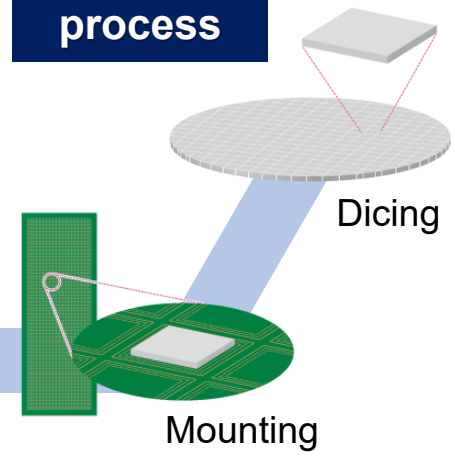
Front-end process



TOWA LASER FRONT
Wafer Marker (Hard)

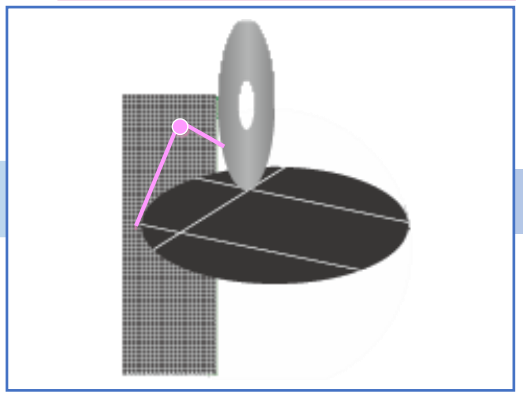
TOWA LASER FRONT
Wafer Marker (Soft)

Back-end process



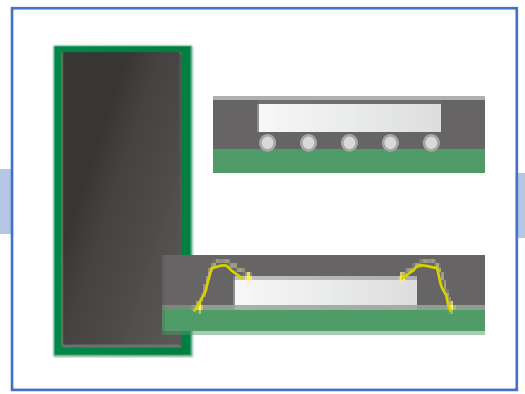
TOWA

Singulation



Each chip is cut out from a frame.

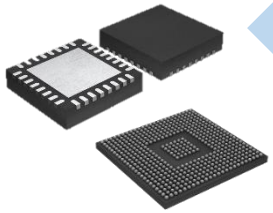
Molding



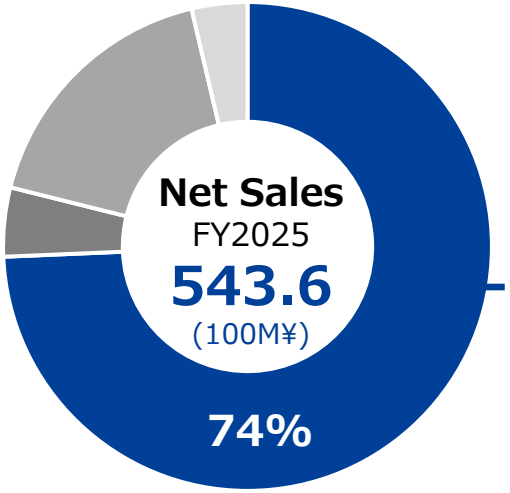
Chips are molded by resin.

After inspection process,

Complete!

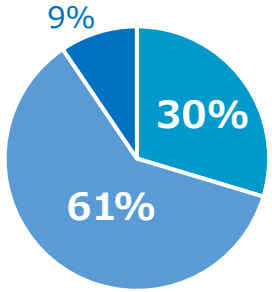


Semiconductor Business



Semiconductor Business

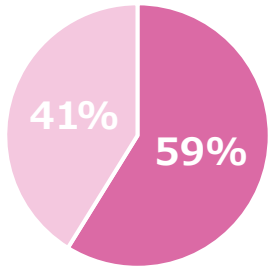
403.9 (100M¥)



- Precision molds
- Molding equipment
- Singulation equipment

Molding equipment and Precision molds

364.6 (100M¥)

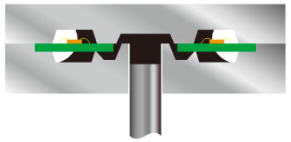


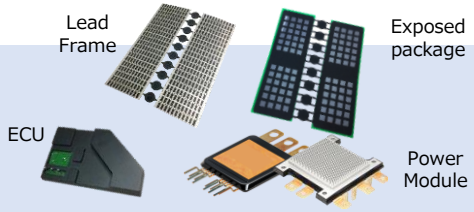
- Transfer equipment and molds
- Compression equipment and molds

Molding

Transfer Molding

Molding method in which the resin is melted in a pot and filled into a cavity to be hardened.



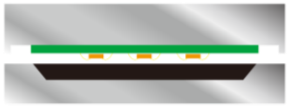


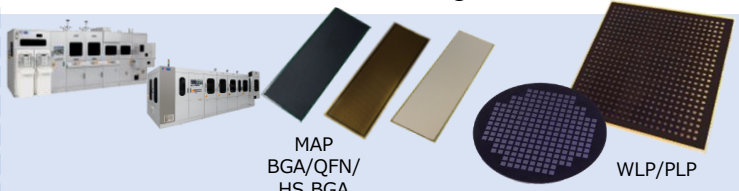
Transfer

Work size (Max.): 100×300mm

Compression molding

Molding method in which the resin is placed directly into the cavity, and then the workpiece is immersed into the cavity after the resin is melted for resin molding.



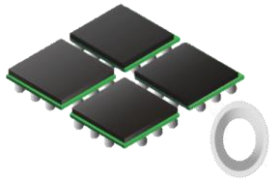


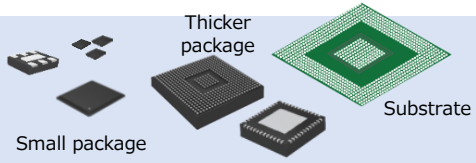
Compression

Work size (Max.): 660×620mm

Singulation

Dicing and storing process for molded products by transfer or compression molding methods.





Singulation

Package size (Min.): 1×1 mm

New Business

Create new market and develop new business

TSS Business

(Total Solution Service)

Propose kinds of solutions such as after sales service, refurbishment, fixing of TOWA's semiconductor manufacturing equipment and used equipment sales.

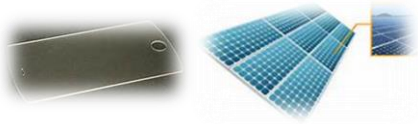
All molding process all over the world to TOWA!!

- **Life Extension Program**
- **Used equipment sales**
- **Prevention & Upkeep (year to year basis contract)**
- **Parts provision**
- **Training Center**

Coating Business

Apply TOWA's original mold surface processing technologies to medical products and domestic articles.

Expand share in pill pressing machine



Expand share in glass products

Nano tech Business

Apply ultra precise and fine processing technology used in ultra precision mold processing to medical and automobile fields.

Develop products in bacteria cultivation business

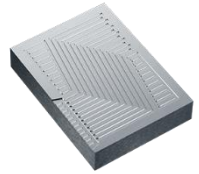
Develop lenses for Head Up Display

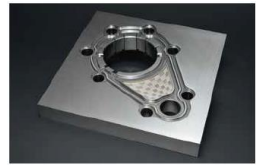
Develop lens for air picture projection

Tooling Business

Sell tools developed in house and incorporate TOWA's know-how as a mold manufacturer.

CBN・Ultra hard end mill





Processing by undertaking customer order

Fusion of a 3D printer and TOWA's too

Medical Device Business

Company Name	BANDICK CORPORATION
Business	Manufacturing of medical plastic molded products Assembly of medical equipment
Address	596-146 Shimojo Minamiwari, Tatsuoka-cho, Nirasaki-shi, Yamanashi
Acquisition Date	November 18, 1983

President & CEO	Toshihiro Terauchi
Number of Employees	100 (as of March 2026)

Main Products

Medical plastic molded product

Plastic molding process using ultra-precision mold technology and proprietary technology

Assembling and production in a clean room

Laser processing machine business

Company Name	TOWA LASERFRONT Corporation
Business	Development, Design, Manufacturing, Sales and Maintenance of Laser & Laser Processing machines
Address	1120, Shimokuzawa, Chuo-ku, Sagamihara-shi, Kanagawa
Acquisition Date	August 1, 2018

President & CEO	Masahiro Iwai
Number of Employees	105 (as of March 2026)

Main Products

Laser Trimmer	Wafer Marker	Laser Welder
		

Combine laser related technology and back-end semiconductor technology to create new market

TOWA × LASERFRONT

Enhance manufacturing capacity and service by utilizing global manufacturing and sales companies

Factories

● TOWA　● Affiliated Companies

Korea

● TOWA KOREA Co., Ltd.
» Manufacturing of equipment, precision mold and component

● TOWA FINE Co., Ltd.
»Manufacturing of blade

China

● TOWA (Suzhou) Co., Ltd.
»Manufacturing of equipment and precision mold

● TOWA (Nantong) Co., Ltd.
»Manufacturing of equipment and precision mold

Malaysia

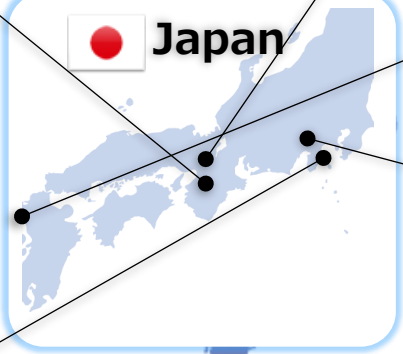
● TOWAM Sdn. Bhd.
»Manufacturing of equipment

● TOWA TOOL Sdn. Bhd.
»Manufacturing of mold

Kyoto (Kyoto-shi)

● Headquarters/Factory
»Develop/manufacture of equipment and precision mold

Japan



Kanagawa (Sagamihara-shi)

● TOWA LASERFRONT Corporation
»Develop/manufacture of laser & laser processing machines

Kyoto (Ujitawara-cho)

● Kyoto East Plant
»Manufacturing of mold

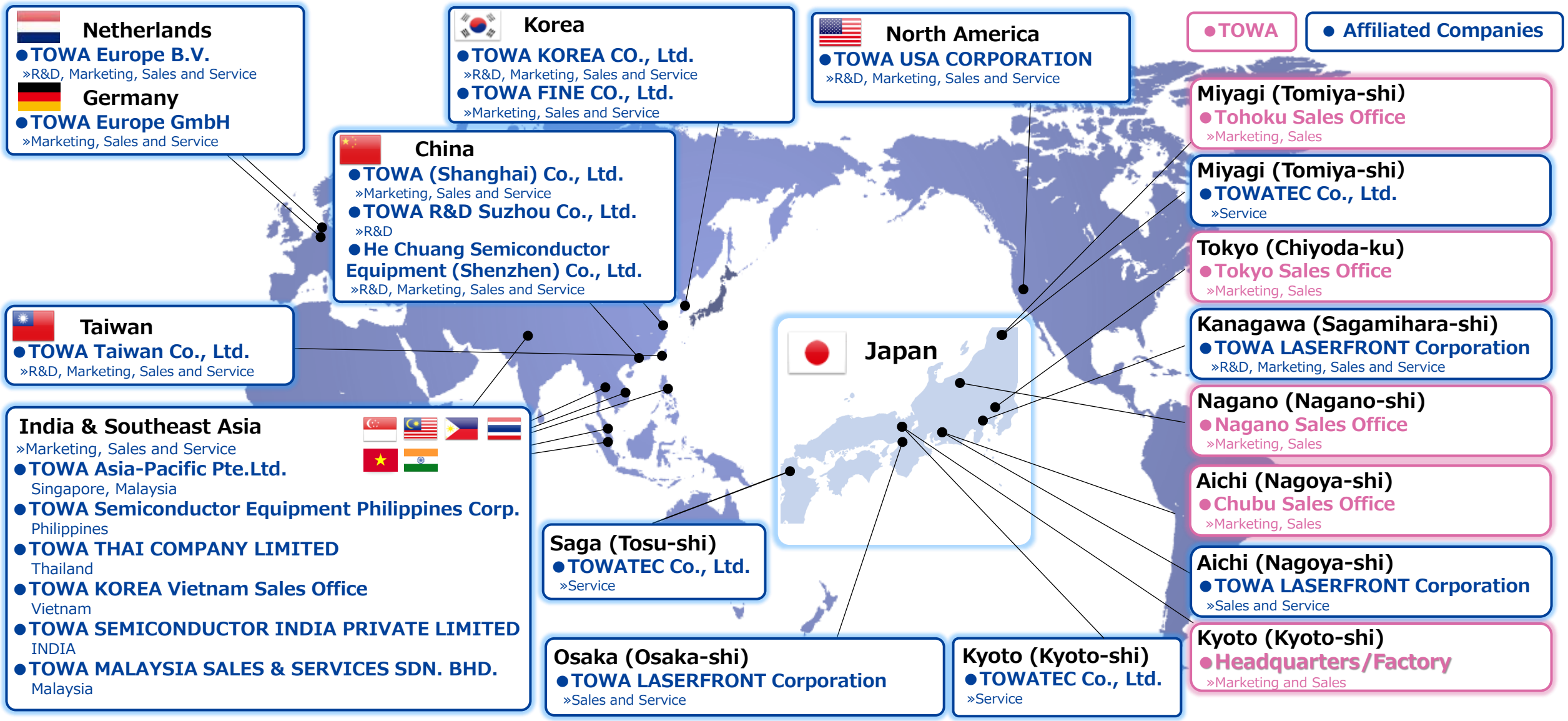
Saga (Tosu-shi)

● Kyushu Work
» Manufacturing of mold

Yamanashi (Nirasaki-shi)

● BANDICK Corporation
»Manufacturing of fine plastic products

Sales/Service facility



● TOWA ● Affiliated Companies

Netherlands
- ● TOWA Europe B.V.
  »R&D, Marketing, Sales and Service

Germany
- ● TOWA Europe GmbH
  »Marketing, Sales and Service

Korea
- ● TOWA KOREA CO., Ltd.
  »R&D, Marketing, Sales and Service
- ● TOWA FINE CO., Ltd.
  »Marketing, Sales and Service

North America
- ● TOWA USA CORPORATION
  »R&D, Marketing, Sales and Service

China
- ● TOWA (Shanghai) Co., Ltd.
  »Marketing, Sales and Service
- ● TOWA R&D Suzhou Co., Ltd.
  »R&D
- ● He Chuang Semiconductor Equipment (Shenzhen) Co., Ltd.
  »R&D, Marketing, Sales and Service

Taiwan
- ● TOWA Taiwan Co., Ltd.
  »R&D, Marketing, Sales and Service

India & Southeast Asia
»Marketing, Sales and Service
- ● TOWA Asia-Pacific Pte.Ltd.
  Singapore, Malaysia
- ● TOWA Semiconductor Equipment Philippines Corp.
  Philippines
- ● TOWA THAI COMPANY LIMITED
  Thailand
- ● TOWA KOREA Vietnam Sales Office
  Vietnam
- ● TOWA SEMICONDUCTOR INDIA PRIVATE LIMITED
  INDIA
- ● TOWA MALAYSIA SALES & SERVICES SDN. BHD.
  Malaysia

Japan

Saga (Tosu-shi)
- ● TOWATEC Co., Ltd.
  »Service

Osaka (Osaka-shi)
- ● TOWA LASERFRONT Corporation
  »Sales and Service

Kyoto (Kyoto-shi)
- ● TOWATEC Co., Ltd.
  »Service

Miyagi (Tomiya-shi)
- ● Tohoku Sales Office
  »Marketing, Sales

Miyagi (Tomiya-shi)
- ● TOWATEC Co., Ltd.
  »Service

Tokyo (Chiyoda-ku)
- ● Tokyo Sales Office
  »Marketing, Sales

Kanagawa (Sagamihara-shi)
- ● TOWA LASERFRONT Corporation
  »R&D, Marketing, Sales and Service

Nagano (Nagano-shi)
- ● Nagano Sales Office
  »Marketing, Sales

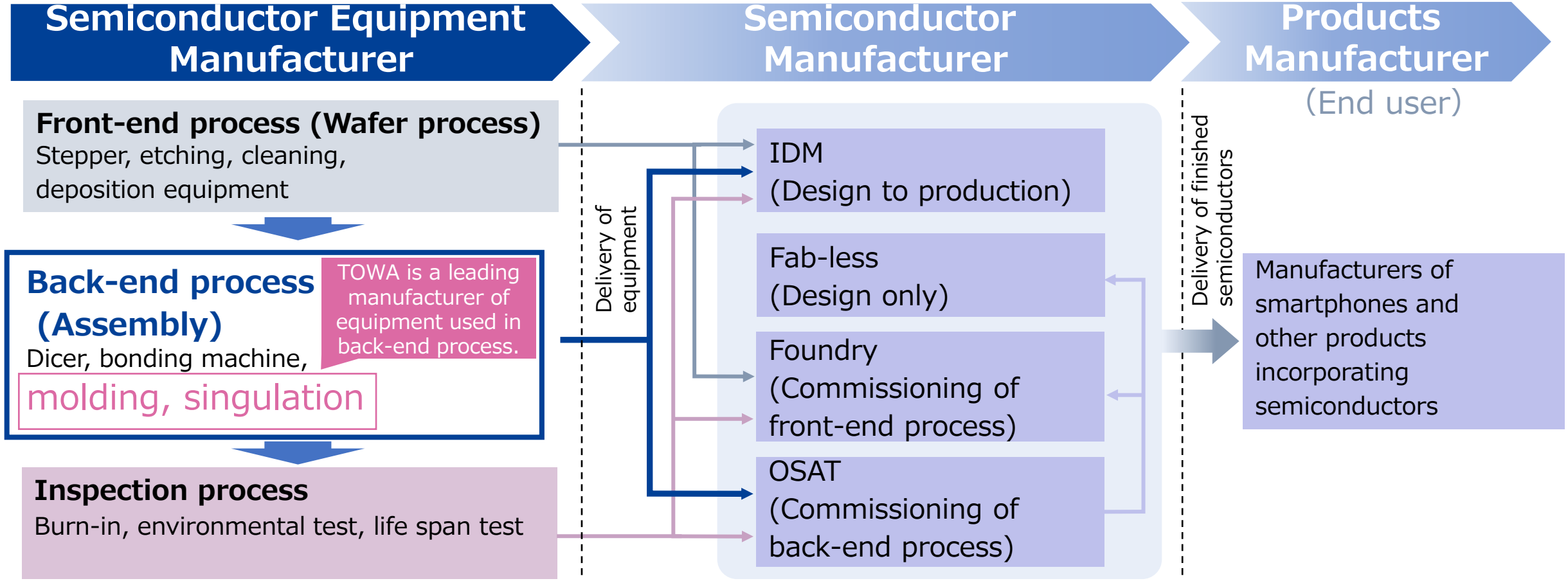
Aichi (Nagoya-shi)
- ● Chubu Sales Office
  »Marketing, Sales

Aichi (Nagoya-shi)
- ● TOWA LASERFRONT Corporation
  »Sales and Service

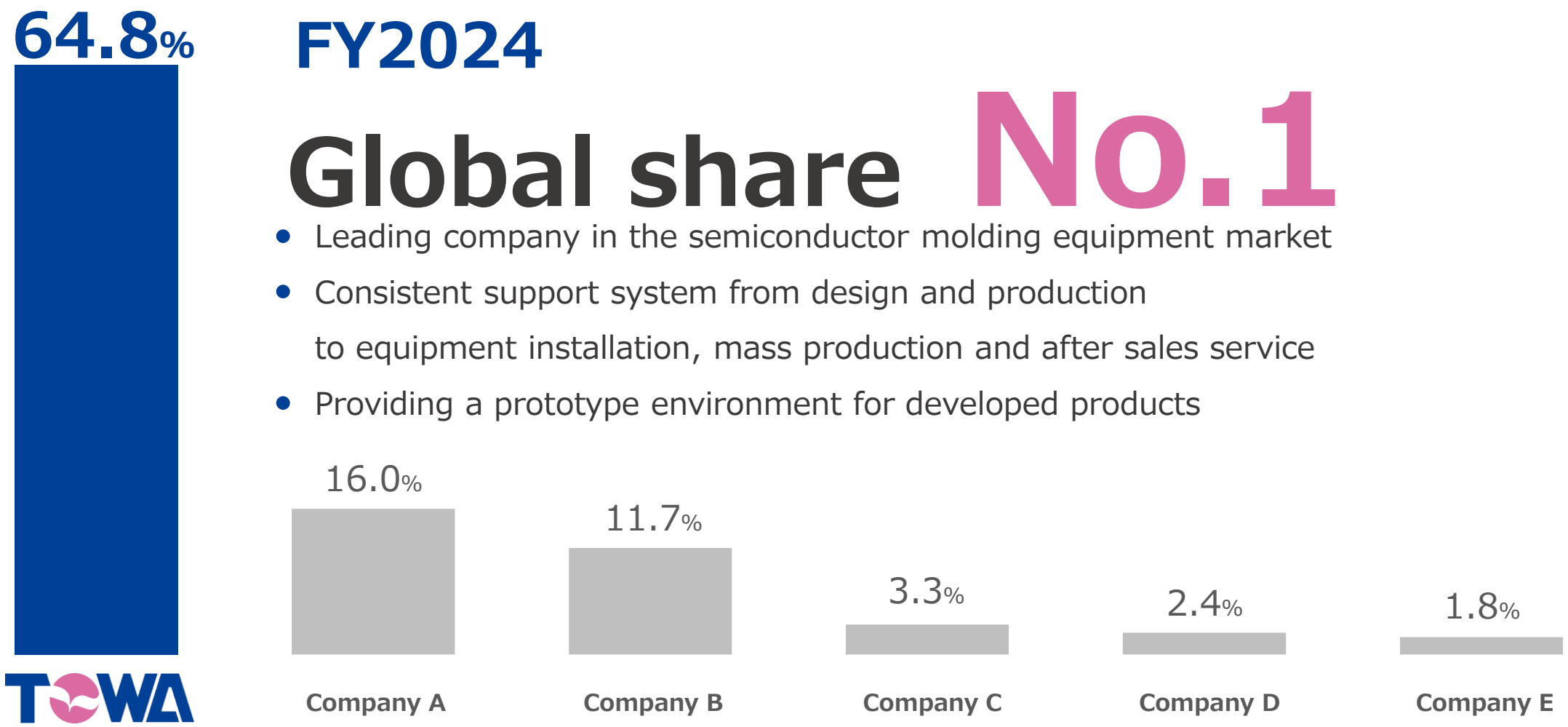
Kyoto (Kyoto-shi)
- ● Headquarters/Factory
  »Marketing and Sales

TOWA Group's Position in Semiconductor Manufacturing

Semiconductor equipment manufacturers can be classified as those producing specialized equipment for wafer (front-end) process, assembly (back-end) process, or inspection process, which they provide to semiconductor manufacturers. The semiconductors these manufacturers produce with this equipment are further supplied to downstream manufacturers who incorporate these semiconductors into their own products. The TOWA Group is a manufacturer of semiconductor equipment used in the back-end process.



Global share of semiconductor molding equipment



FY2024

Global share No.1

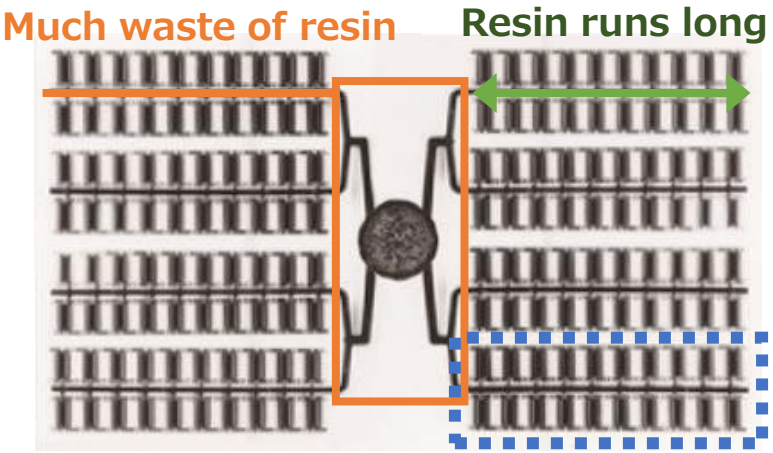
- Leading company in the semiconductor molding equipment market
- Consistent support system from design and production to equipment installation, mass production and after sales service
- Providing a prototype environment for developed products

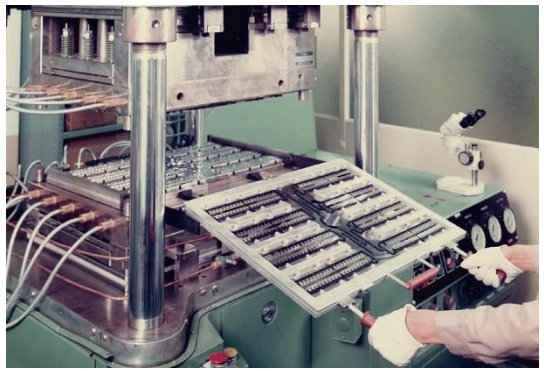
*Created by our company based on data from TechInsights

Molding innovation I (1979)

Conventional Mold

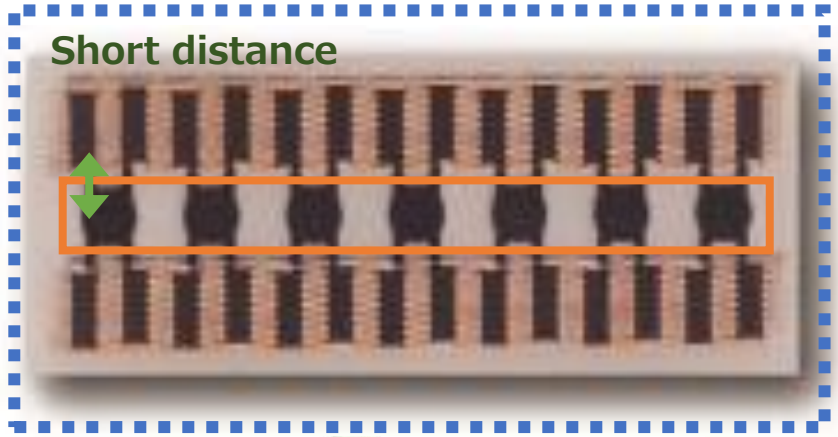
Manual molding by putting one palm size resin into the central pod. Resin runs long distance. Molding quality is not homogeneous. And much waste of resin.





Multi-Plunger Mold

Auto molding by putting finger size resins into several pods. This realized short runner, homogeneous molding quality and less waste of resin.



Molding innovation II (1995)

Module System (Y series)

Before the development of Module System,
Molding equipment was･･･

Each equipment is designed depends on what or how much it will manufacture.
Semiconductor manufacturers had to buy another equipment ,
when they want to manufacture another type of product or increase their product volume.

2 Module Connection

Module System enables to adjust press number!!

・Even you have only one Y series machine,
you can manufacture many types of products or increase your product volume.

4 Module Connection

Y series is sufficient to meet the needs of assembly subcontractor, to perform backend process bringing from IDM.

Semiconductor molding equipment is one of the strongest quality of TOWA.

Molding innovation III (2009)

Compression Molding Equipment

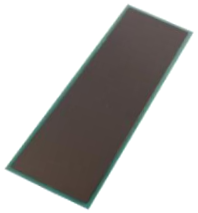
Independent compression molding technology has enabled to mold cutting-edge devices, and cut the cost significantly!!

The compression technology is unrivaled from its launch in 2009 because of the patent and technical difficulty.

Features

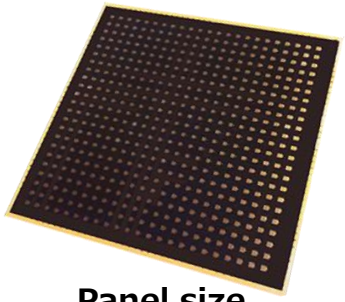
- 100% resin efficiency
  (CO2 emissions reduced by about 70%)
- Compression molding with no resin fluidity
  (reduce defective products)
- Most suitable for cutting-edge such as memory and 5G
- Applicable to both granular type and liquid type resin
- Applicable to both panel size and wafer size

Compression Equipment
Model PMC 2030-D



Substrate size
100×300mm

Wafer size
φ300mm



Panel size
600mm×600mm

Semiconductor Manufacturing Equipment Line-Up

～Compression Mold～

Compression Equipment
Model CPM 1180

Work max size：660×620mm

Compression Equipment
Model CPM 1080

Work max size：φ300mm, 320x320mm

Compression Equipment
Model PMC 2030-D

Work max size：100x300mm

～ Transfer Mold～

Transfer Equipment
Model YPM 1180

Work max size：100x300mm

Transfer Equipment
Model YPM1250-EPQ

Work max size：□150mm, 100x300mm

～ Singulation～

Singulation Equipment
Model FMS 4040

Work max size：100x300mm